DiAPLEX

SHAPE MEMORY POLYMER

POTTING AND CURING CONDITONS

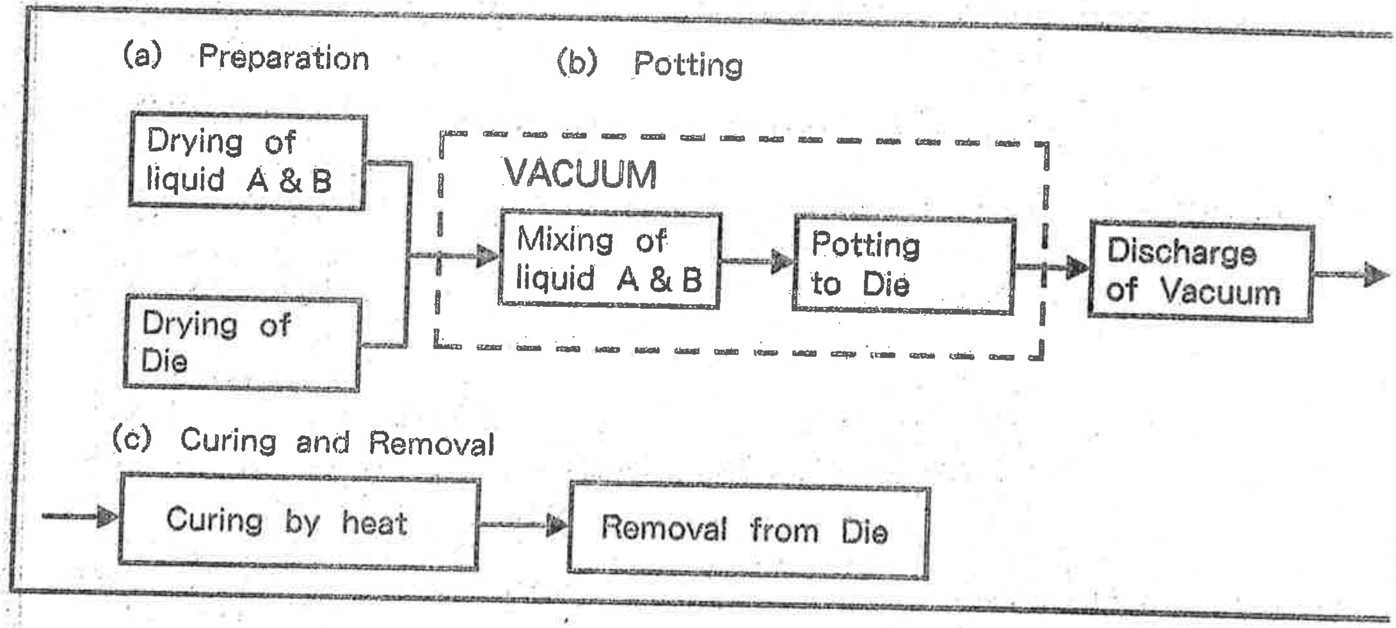
MOLDING INSTRUCTIONS

1. Products

MP – 25xx Series (Tg 25 ℃)
MP – 35xx Series (Tg 35 ℃)
MP – 45xx Series (Tg 45 ℃)
MP – 55xx Series (Tg 55 ℃)

Each product consists of two liquid types : A : Resin, B : Hardner

2. Potting and Curing Conditions



(a) Preparation

- Dry liquid A and B for more than 1 hour at less than 50 Torr.
- Dry the die for more than 1 hour at 70 ℃.

(b) Potting

- Place liquid A and B into vacuum chamber of less than 50 Torr.
- Mix liquid A and B, stirring for 30 sec. at 60 rpm.
- Immediately after stiring, pot the mixed solution to the die.
- After confirming that the solution flows into the die completely, discharge the vacuum.

(c) Curing and Removal

- Remove the die from vacuum chamber to the temperature and place into chamber.
- Cure the material for 1 – 2 hours at 70 ℃
- Remove the finished product from the die.
- If necessary, cure an additional 1 – 2 hours at 70 ℃.

(d) Cleaning

- Methylene chloride is recommended.

GRADE OF POTTING MATERIALS

Grade	Mixing[*1] Ratio	Viscosity (cps/25C)	Specific Gravity	Pot life[*2]
MP – 2510	A 100 B 100	135 220	1,066 1,216	5'00"
MP – 3510	A 100 B 100	1,410 290	1,066 1,216	4'30"
MP – 4510	A 100 B 100	1,280 200	1,066 1,218	3'30"
MP – 5510	A 40 B 60	150 60	1,062 1,215	6'00"

[*1] A = Resin, B = Hardner
[*2] 100gr/25C Curing time